

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
<b>CONVEYING PARTY DATA</b>									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>A Leam Choi</td> <td>06/23/2011</td> </tr> <tr> <td>DongSam Park</td> <td>06/23/2011</td> </tr> <tr> <td>YongDuk Lee</td> <td>06/23/2011</td> </tr> </tbody> </table>		Name	Execution Date	A Leam Choi	06/23/2011	DongSam Park	06/23/2011	YongDuk Lee	06/23/2011
Name	Execution Date								
A Leam Choi	06/23/2011								
DongSam Park	06/23/2011								
YongDuk Lee	06/23/2011								
<b>RECEIVING PARTY DATA</b>									
Name:	STATS ChipPAC Ltd.								
Street Address:	10 Ang Mo Kio Street 65								
Internal Address:	#05-17/20 Techpoint								
City:	Singapore								
State/Country:	SINGAPORE								
Postal Code:	569059								
<b>PROPERTY NUMBERS Total: 1</b>									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13167631</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13167631				
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Application Number:	13167631								
<b>CORRESPONDENCE DATA</b>									
Fax Number:	(408)738-0881								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	408-738-0592								
Email:	efiling@ishimarulaw.com								
Correspondent Name:	LAW OFFICES OF MIKIO ISHIMARU								
Address Line 1:	2055 GATEWAY PLACE								
Address Line 2:	SUITE 700								
Address Line 4:	SAN JOSE, CALIFORNIA 95110								
ATTORNEY DOCKET NUMBER:	27-815								
NAME OF SUBMITTER:	Mikio Ishimaru								
Total Attachments: 3 source=27-815_Assignment#page1.tif source=27-815_Assignment#page2.tif source=27-815_Assignment#page3.tif									

**CH \$40.00 13167631**

## ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

### **INTEGRATED CIRCUIT PACKAGING SYSTEM WITH VERTICAL INTERCONNECTS AND METHOD OF MANUFACTURE THEREOF**

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

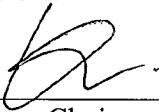
NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

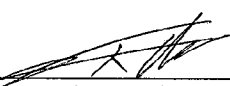
1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this Non Provisional application in the spaces that follow:

Serial Number: 13/167,631 Filing Date: June 23, 2011

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

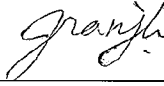
  
 \_\_\_\_\_  
 A Leam Choi

  
 \_\_\_\_\_  
 Witness Signature

Choi DaeSik  
 \_\_\_\_\_  
 Print Witness Name

Jun-23-2011  
 \_\_\_\_\_  
 Date

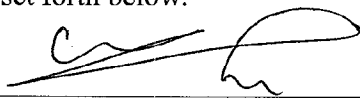
Jun. 23. 2011  
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 Date

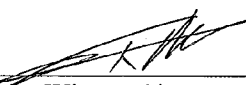
  
 \_\_\_\_\_  
 Witness Signature

Hoon JUNG  
 \_\_\_\_\_  
 Print Witness Name

Jun-23-2011  
 \_\_\_\_\_  
 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.


  
 \_\_\_\_\_  
 DongSam Park

  
 \_\_\_\_\_  
 Witness Signature

Choi DaeSik  
 \_\_\_\_\_  
 Print Witness Name

Jun-23-2011  
 \_\_\_\_\_  
 Date

Jun. 23. 11  
 \_\_\_\_\_  
 Date

  
 \_\_\_\_\_  
 Witness Signature

Hoon JUNG  
 \_\_\_\_\_  
 Print Witness Name

Jun-23-2011  
 \_\_\_\_\_  
 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



YongDuk Lee

6.23.2011

Date



Witness Signature

Choi DaeSik

Print Witness Name

Jun-23-2011

Date



Witness Signature

Hoon JUNG

Print Witness Name

Jun-23-2011

Date